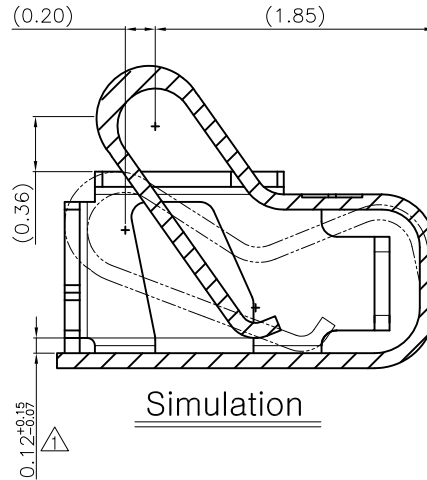
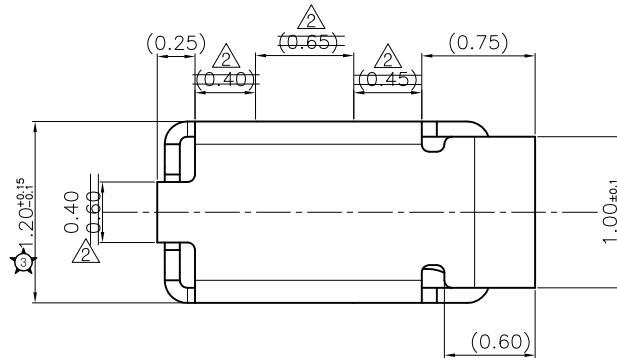
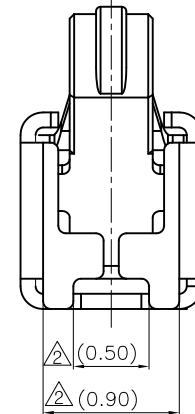
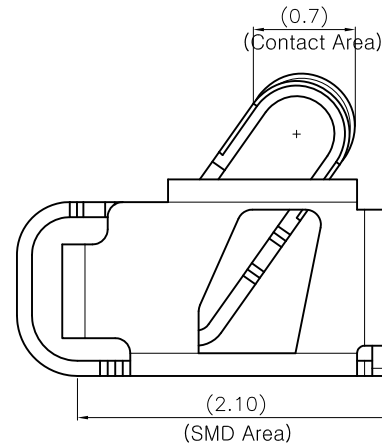
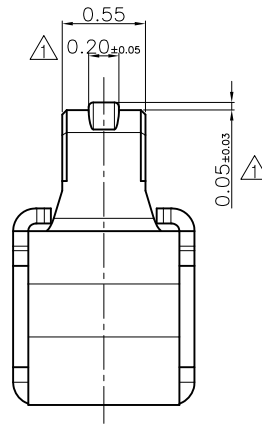
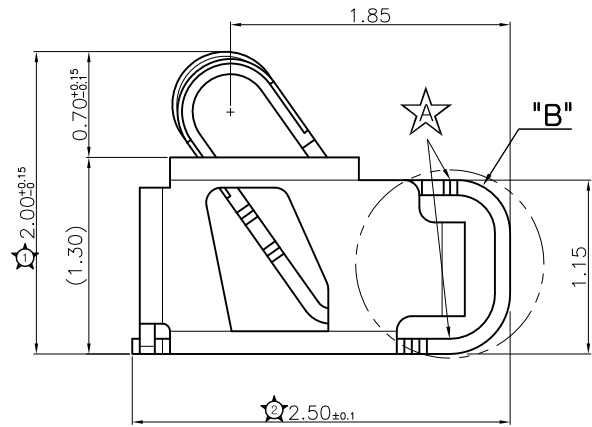
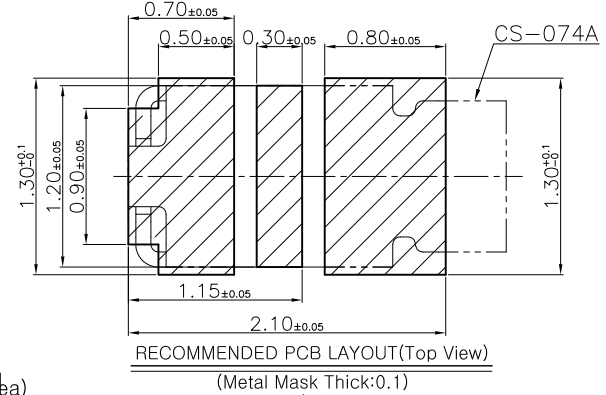
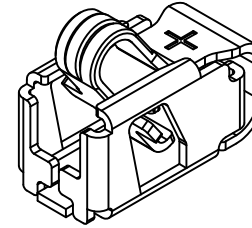
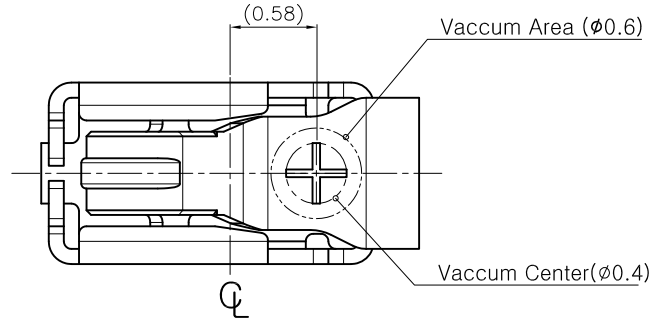


Rev No.	Description	Date	Name	Reviewed	Approved	Remark
△ X 3	고객사 요청으로 인한 Spec' 추가	2015.05.07	M.G.Son	Y.J.Park	S.K.Hong	-
△ X 6	고객사 요청으로 인한 Wall 무너짐 개선	2015.06.01	M.G.Son	Y.J.Park	S.K.Hong	-



- *NOTE
1. PLATING
 - Contact Area : Au 0.05 μ m Min. over Pd-Ni 0.2 μ m Min. over Ni 1.5~4.0 μ m
 - SMD Area : Au 0.05 μ m Min. over Ni 1.5~4.0 μ m
 - Other Area : Ni 1.5~3.5 μ m
 2. ☆: C.T.Q
 3. ☆: 평탄도 0.05 Max.
 4. Contact 가동거리 : 0.7mm
권장 Contact 높이 : 가동거리의 60~90% 범위 내
(0.42~0.63mm) => (1.37~1.58mm)
 5. 제품의 안정적 Contact을 위하여 Bending部 "B" 주위에 기구적인 간섭이 없을 것.



1	Contact	Ti-Cu Alloy				Note. 1			t0.1	
No	Part name	Material				Finish			Remarks	
General Tolerance		Scale	N/S	Units	mm		TITLE	CS-074A		
Dimension	mm (°)	Date		2015. 04. 09				ANTENNA CONTACT		
X	± 0.2	Drawn	Design	Checked	Reviewed	Approved		Customer Drawing		
X.X	± 0.15									
X.XX	± 0.1									
X.XXX	± 0.05									
ANGLE	± 2°	J.K. Park			Y.J. Park	S.K. Hong	SW No.	RI-CS-074A-A1.DWG		Rev.
 협진커넥터(주) HYUPJIN CONNECTOR Co., Ltd.		Sheet 1 of 1		DWG No.	CS-074A-A1		2			

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